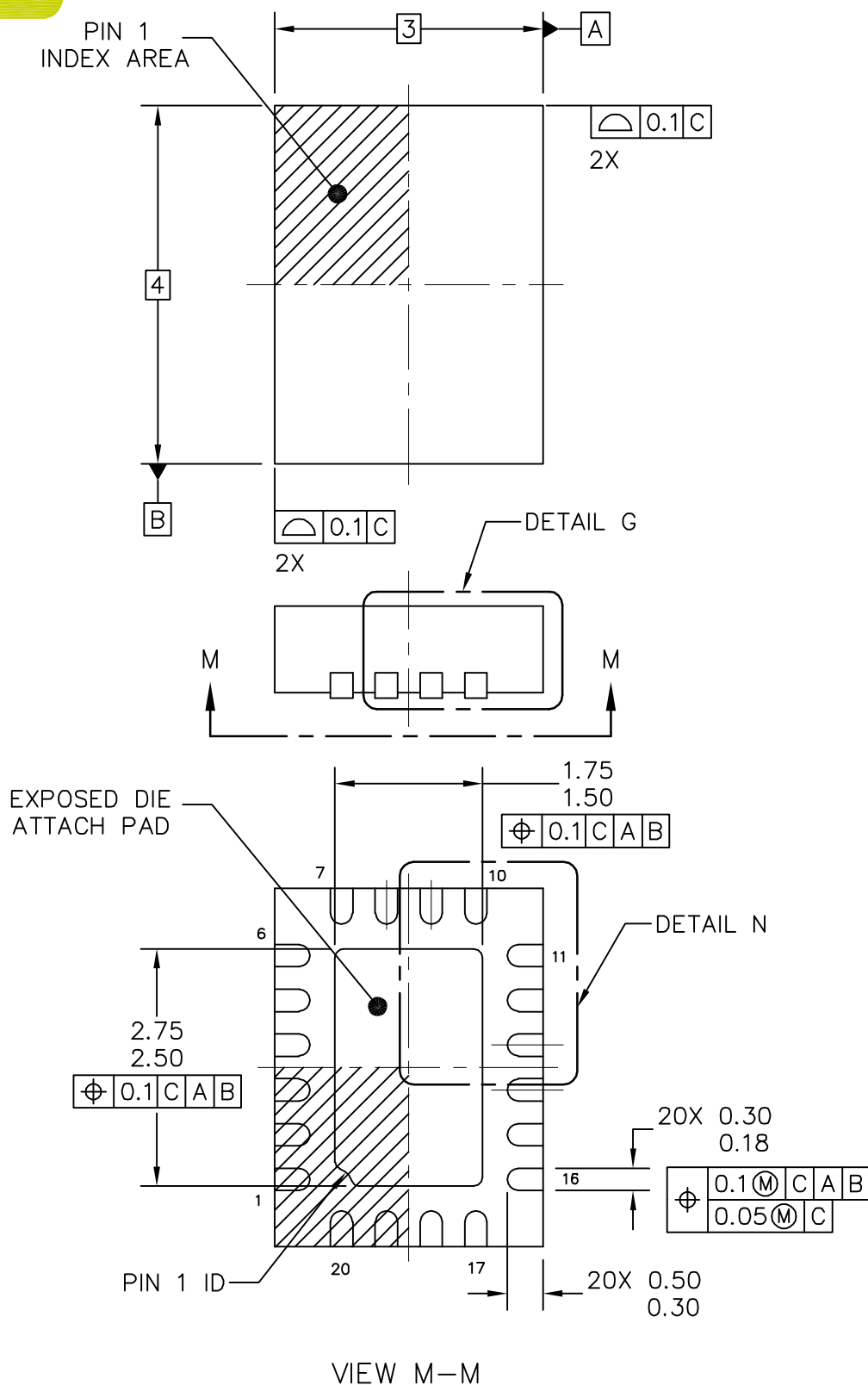




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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.50 PITCH (3 X 4 X 0.65) CASE OUTLINE		DOCUMENT NO: 98ASA00050D	REV: C
		STANDARD: NON-JEDEC	
		SOT1583-1	05 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
4. DELETED

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